



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-12-05
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC8H065B-TR	7ZDP*3D131T6	A	3068	2017-12-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	320.00	mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.11	Die / Leadframe	331
Lead	2.04	Soft Solder	6369
Cobalt	0.46	Leadframe	1444
Antimony trioxide	1.77	Mold compound	5531

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	7ZDP*3D131T6					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.485	mg	supplier	die	Sillicium carbide	409-21-2		3.401	mg	975904	10631
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	5737	63
				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	860	9
				supplier	metallization	Silver (Ag)	7440-22-4		0.033	mg	9466	103
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	287	3
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	287	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	861	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.014	mg	4016	44
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.009	mg	2582	23
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	994601	512975
Leadframe	Copper & its alloys	165.043	mg	supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1999	1031
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2799	1444
				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	559	288
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	22
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	2.038	mg	955014	6369
Soft solder	Solder	2.134	mg	supplier	solder	Silver (Ag)	7440-22-4		0.053	mg	24836	166
				supplier	solder	Tin (Sn)	7440-31-5		0.043	mg	20150	134
				supplier	wire	Aluminium (Al)	7429-90-5		1.200	mg	1000000	3750
Bonding wires	Other inorganic materials	1.200	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.200	mg	1000000	3750
				supplier	mol d compound	Silica, vitreous	60676-86-0		118.556	mg	805993	370488
				supplier	mol d compound	Epoxy Cresol Novolak	29690-82-2		10.296	mg	69997	32175
				supplier	mol d compound	Phenol resin	9003-35-4		5.884	mg	40002	18388
				supplier	mol d compound	Biphenyl epoxy resin	85954-11-6		8.826	mg	60003	27581
				supplier	mol d compound	Antimony Trioxide	1309-64-4		1.765	mg	11999	5516
				supplier	mol d compound	Brominated Epoxy Resin	40039-93-8		1.030	mg	7002	3219
				supplier	mol d compound	Carbon black	1333-86-4		0.736	mg	5004	2300
Encapsulation	Other Organic Materials	147.093	mg	supplier	mol d compound	Carbon black	1333-86-4		0.736	mg	5004	2300
				supplier	mol d compound	Carbon black	1333-86-4		0.736	mg	5004	2300
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266